



GR825-73B

June 2018

PRODUCT DESCRIPTION

GR825-73B provides the following product characteristics:

Technology	Epoxy
Appearance	Black
Cure	Heat cure
Product Benefits	• Green product
Filler Weight, %	80
Typical Package Application	SOIC, SOP, SSOP and QSOP
Application	Molding compound
Flammability	94 V-0

GR825-73B is a epoxy cresol novolac type, semiconductor grade molding compound. GR825-73B epoxy molding compound contains no bromine, antimony or phosphorus flame retardant. This material is designed to achieve JEDEC Level 1 requirements, at 260°C reflow temperature. It has been specifically designed for lead frame packages with nickel palladium gold or copper silver spot metallization.

GR825-73B meets UL 94 V-0 Flammability at 3mm thickness.

TYPICAL PROPERTIES OF UNCURED MATERIAL

Gel Time @ 175 °C, seconds	22
Spiral Flow, @ 175°C, cm	100
Shelf Life:	
@ 5°C, months	6

TYPICAL PROCESS DATA

Handling

Preheat Temperature :	
Conventional mold, °C	85 to 100
Automold, seconds	0 to 5
Molding Temperature, °C	170 to 180
Molding Pressure, Kg/cm ²	40 to 80
Transfer Time:	
Conventional mold, seconds	15 to 25
Automold, seconds	5 to 10
Curing Time, 3 mm section:	
Conventional mold:	
@ 175°C, seconds	70 to 100
Automold:	
@ 175°C, seconds	50 to 90
Post Cure @ 175°C, hours	2 to 6

GR825-73B has been formulated to provide the best possible moldability and as wide a molding latitude as possible. Although molding and curing conditions will vary from situation to situation, recommended starting ranges are shown above.

TYPICAL PROPERTIES OF CURED MATERIAL

All measurements taken at 25 °C unless otherwise noted. All physical, electrical and analytical measurements taken on specimens cured for 2 minutes @ 175 °C with post cure of 6 hours at 175 °C, unless otherwise specified.

Physical Properties:

Coefficient of Thermal Expansion, cm/°C :	
Below Tg	12×10 ⁻⁶
Above Tg	45×10 ⁻⁶
Glass Transition Temperature, °C	135
Specific Gravity	1.9
Molded shrinkage, as molded, %	0.25
Flexural Strength Kg/mm ² :	
@ 25 °C	12
Flexural Modulus Kg/mm ² :	
@ 25 °C	1,900
Thermal Conductivity, W/mk	0.8
Moisture Absorption, %:	
168 hours @ 85°C/85% RH	0.32

Electrical Properties:

Volume Resistivity, ohms-cm, 500 volts:	
@ 22°C	11×10 ¹⁵

GENERAL INFORMATION

For safe handling information on this product, consult the Material Safety Data Sheet, (MSDS).

This product is not recommended for use in pure oxygen and/or oxygen rich systems and should not be selected as a sealant for chlorine or other strong oxidizing materials.

Not for product specifications

The technical data contained herein are intended as reference only. Please contact Hysol Huawei Electronics Co., Ltd. quality department for assistance and recommendations on specifications for this product.

Storage

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

Powder Storage - Powder or preforms should be stored at 5°C or below, in closed containers. After removal from cold storage, the material MUST be allowed to come to room temperature, in the sealed container, to avoid moisture contamination. The suggested waiting time for a standard 15 kg carton box is 24 hours.

Material removed from containers may be contaminated during use. Do not return product to the original container. Hysol Huawei Electronics Co., Ltd. cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact Hysol Huawei Technical Service Center or Customer Service Representative.

Disclaimer
NOTE

The information provided in this Technical Data Sheet (TDS) including the recommendations for use and application of the product are based on our knowledge and experience of the product as at the date of this TDS. The product can have a variety of different applications as well as differing application and working conditions in your environment that are beyond our control. Hysol Huawei is, therefore, not liable for the suitability of our product for the production processes and conditions in respect of which you use them, as well as the intended applications and results. We strongly recommend that you carry out your own prior trials to confirm such suitability of our product.

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